



Declaration of Restriction of Hazardous Substance (RoHS) Compliance

We hereby represent that the products and components (including accessories and packages thereof) are conformed to following requirements:

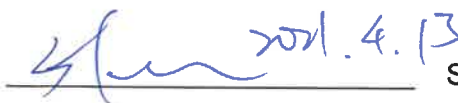
- European RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.
- China RoHS II Directive (GB/T 26572-2011) and the definitions given for the Directive GB/T 26572-2011, by the commission on the restriction of the use of certain hazardous substances in electrical and electronic equipment. Products and components (including accessories and packages thereof), with a date of manufacture on or after 1 July 2016, have to mark with label according to the standard SJ/T 11364-2014 "Marking for the Restricted Use of Hazardous Substances in Electronic and Electrical Products".

Banned Substance	EU RoHS Maximum Limit	China RoHS II Maximum Limit
Lead (Pb)	1,000 ppm (0.1 weight %)	1,000 ppm (0.1 weight %)
Cadmium (Cd)	100 ppm (0.01 weight %)	100 ppm (0.01 weight %)
Mercury (Hg)	1,000 ppm (0.1 weight %)	1,000 ppm (0.1 weight %)
Hexavalent Chromium (Cr ⁶⁺)	1,000 ppm (0.1 weight %)	1,000 ppm (0.1 weight %)
Poly Brominated Biphenyls (PBB)	1,000 ppm (0.1 weight %)	1,000 ppm (0.1 weight %)
Poly Brominated Diphenyl Ethers (PBDE)	1,000 ppm (0.1 weight %)	1,000 ppm (0.1 weight %)
Bis(2-ethylhexyl) phthalate (DEHP)	1,000 ppm (0.1 weight %)	-
Butyl benzyl phthalate (BBP)	1,000 ppm (0.1 weight %)	-
Dibutyl phthalate (DBP)	1,000 ppm (0.1 weight %)	-
Diisobutyl phthalate (DIBP)	1,000 ppm (0.1 weight %)	-

RoHS maximum limit (ppm) does not apply to applications for which exemptions have been granted by EU RoHS Annex III and China RoHS II Exemption List for the Restriction of Hazardous Substances of the Standard Achieving Management Catalogue.

Some components used in fore mentioned products are exempted as listed below:

EU RoHS Exemption	China RoHS II Exemption	Description
6(a)-I	7.1	Lead as an alloying element in steel for machining purposes containing up to 0,35 % lead by weight and in batch hot dip galvanised steel components containing up to 0,2 % lead by weight
6(b)-II	7.2	Lead as an alloying element in aluminium for machining purposes with a lead content up to 0.4 % by weight
6(c)	7.3	Lead as an alloying element in copper alloy containing up to 4 % lead by weight
7(a)	8.1	Lead in high melting temperature type solders
7(c)-I	8.3.1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
15	14	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

 2021.4.13
Steven Wang

Name and signature of authorized person

Position: Quality Management Division/ Director

Date of Issue: April 13th, 2021